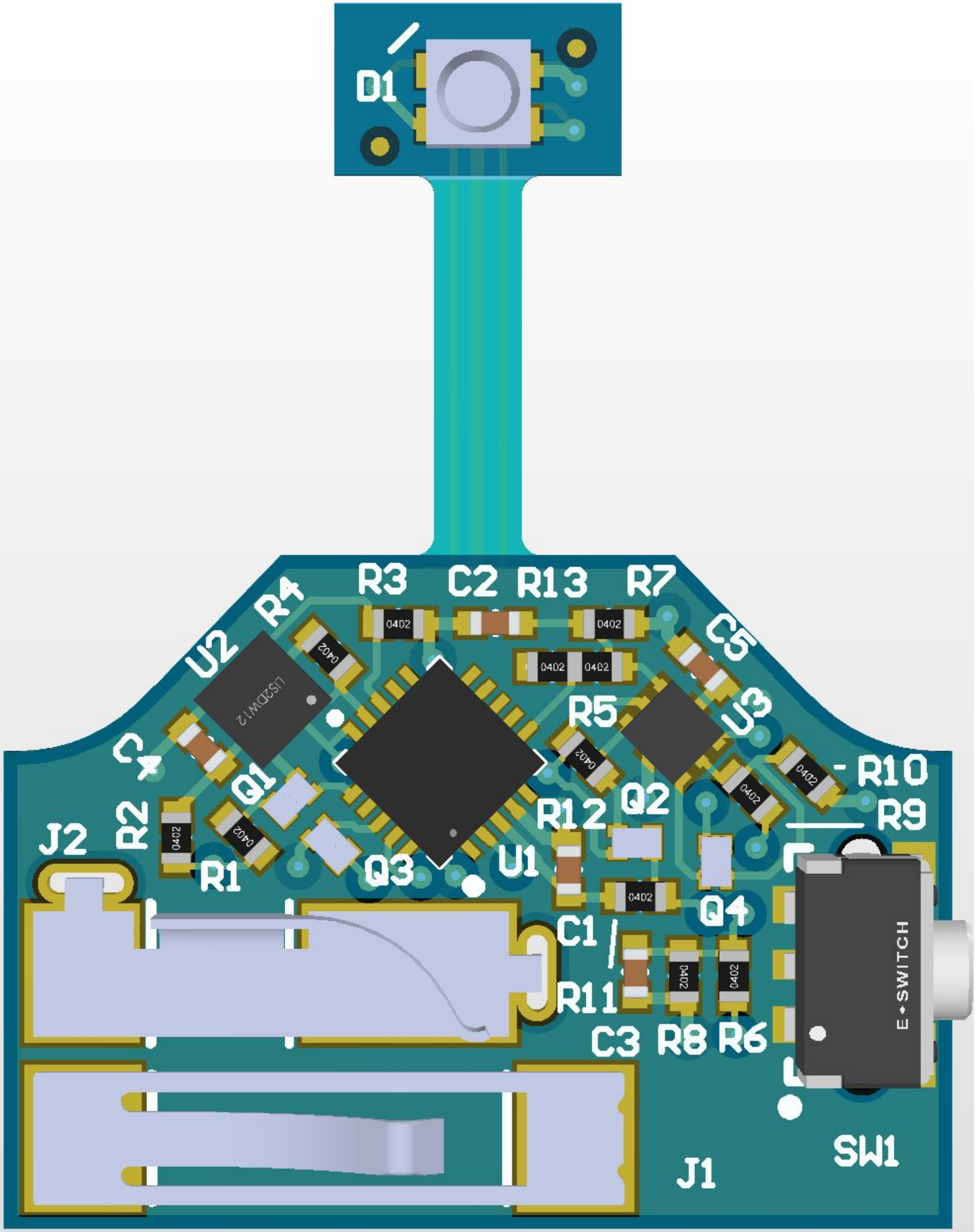
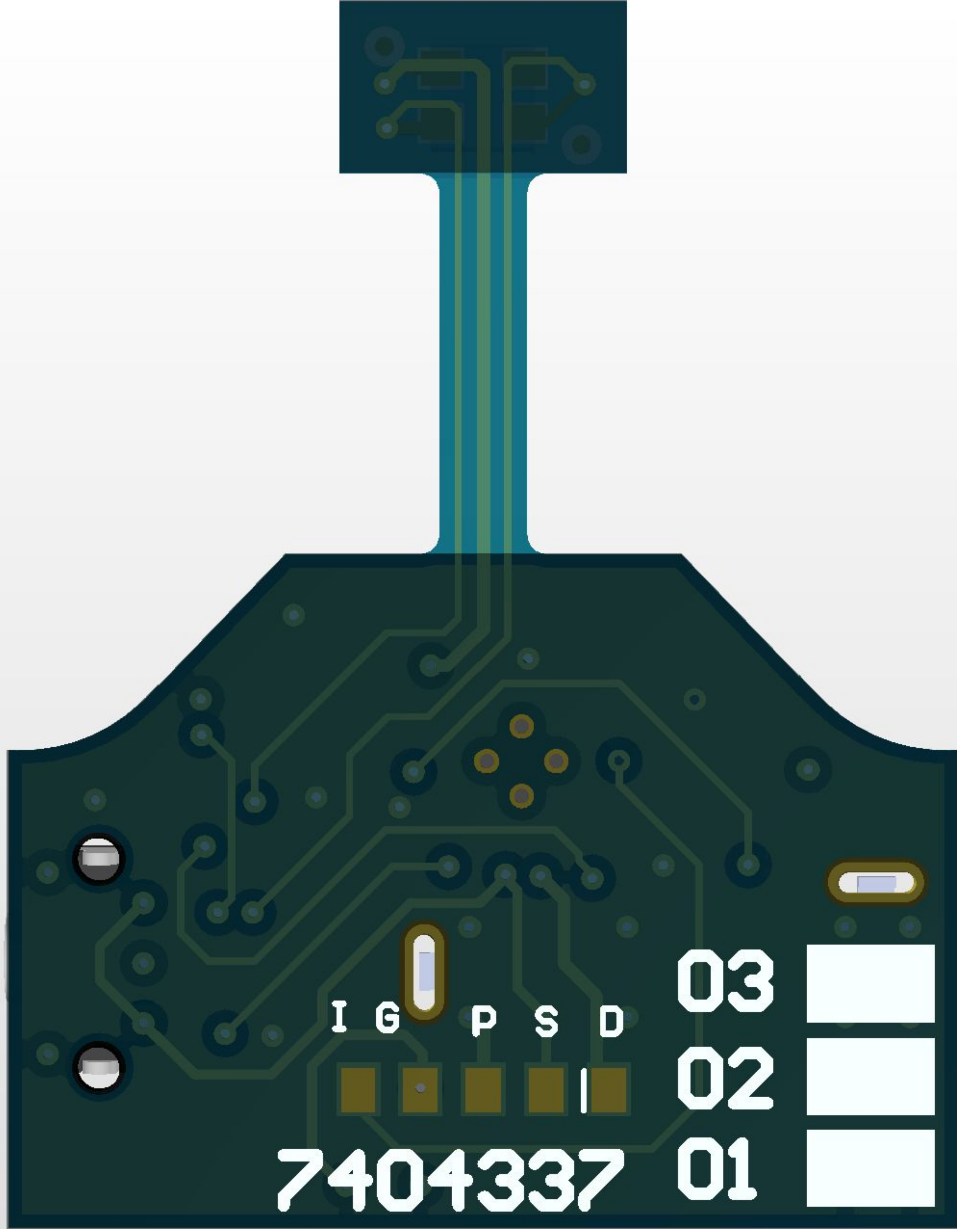
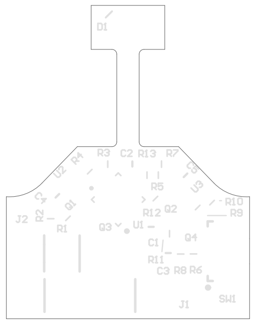
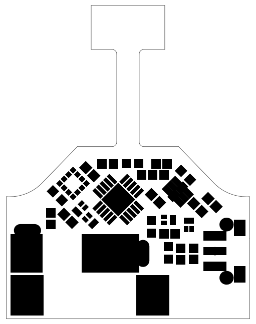

D1
R3
C2
R13
R7
R4
C5
U2
LIS2DW12
R5
U3
C4
R10
Q1
R12
Q2
R9
R2
J2
R1
Q3
U1
Q4
C1
R11
C3
R8
R6
E-SWITCH
SW1
J1
0402


I
G
P
S
D
03
02
01
7404337



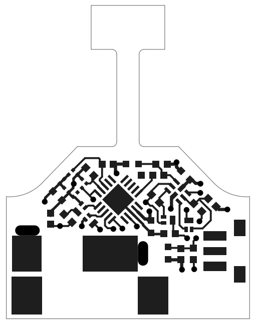
LED Top Overlay

Board Outline



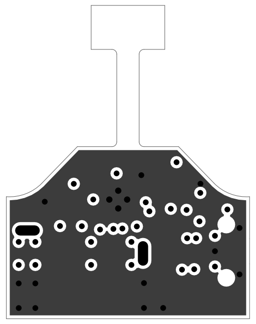
Top Coverlay

Board Outline



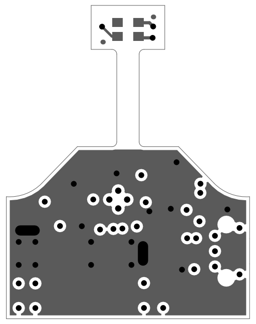
Top Layer 1

Board Outline



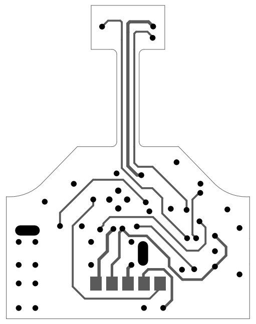
Layer 2

Board Outline



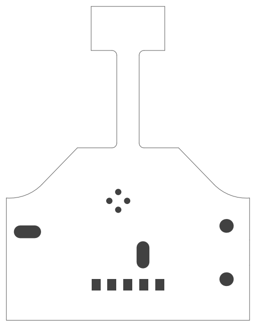
Layer 3/Top LED

Board Outline



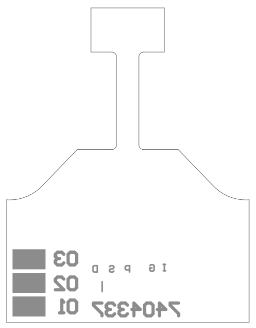
Bottom Layer

Board Outline



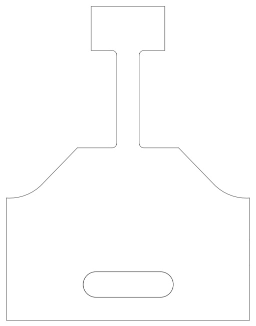
Bottom Coverlay

Board Outline



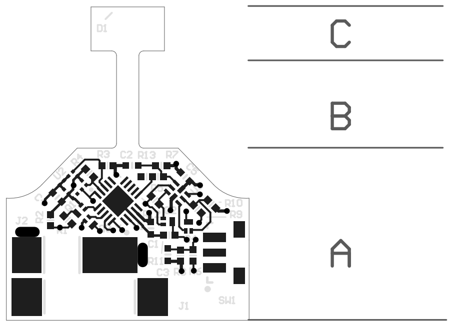
Bottom Overlay

Board Outline



Cutout in Stiffener

Board Outline



Top Layer 1

LED Top Overlay

Fab Notes

Board Outline

PCB Fab Notes (dimensions in mm)---

1. Refer to 7404337 drawing pdf for additional requirements.
2. For PCB stackup ('A', 'B', 'C'), refer to stackup file in Project Outputs > FAB folder.
3. Finish: Exposed conductive pads and traces plated with ENIG per IPC-4552.
4. Soldermask: CM is allowed to alter soldermask expansion as required.
5. Layer-to-layer registration <0.152.
6. PCB to be lead free and RoHS compliant, and compatible with RoHS assembly methods.
7. Inner layer copper pullback from board edge allowed.
8. Silkscreen: white, permanent, non-conductive ink. Keep clear of solder pads.
9. No controlled impedance requirements.
10. Hole tolerance: +/-.076 (drill position); diameter +/-.076 (PTH).
11. Coverlay may be added over black in the C section of stackup to create smaller solder dams to prevent solder bridges.
12. There are two additional files for top paste and solder for the layer 3 top.
13. Stiffener on the bottom side of section A needs a mechanical cutout for 5-pin, see drawing.
14. Mounting slots for J2 show plating through the stiffener that shoudln't be there the plating should not extend to stiffener.
15. Bottom Coverlay Print should be printed on the bottom of the stiffener, not the bottom of the flex circuit.

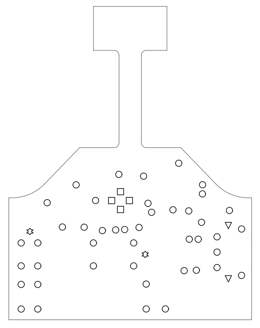
SIG SAUER

18 Industrial Drive Exeter, NH 03833

Title
CIRCUIT BOARD, ROMEO ZERO, GEN2 BOARD

Size A
Number 7404337
Revision 00

Date: 3/30/23
Sheet 1 of 1
File:
Drawn By: MM



DrillDrawing

Board Outline

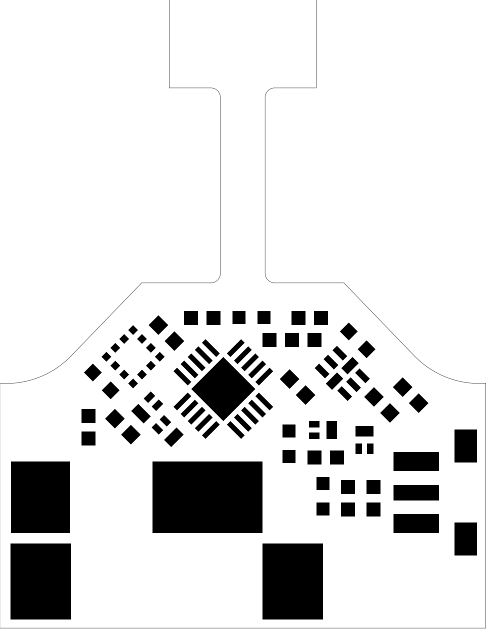
Hole tolerance: +/-.076 (drill position): diameter +/-.076 (PTH).

Symbol	Count	Hole Size	Hole Length	Routed Path Length	Plated	Hole Type
✡	2	17.00mil (0.432mm)	62.00mil (1.575mm)	45.00mil (1.143mm)	PTH	Slot
▽	2	35.00mil (0.889mm)	-	-	NPTH	Round
☐	4	11.81mil (0.300mm)	-	-	PTH	Round
○	44	8.00mil (0.203mm)	-	-	PTH	Round
	52 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

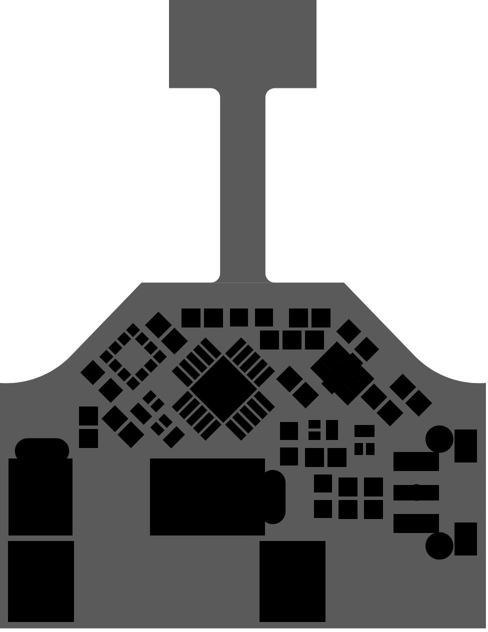
SIG SAUER
18 Industrial Drive Exeter, NH 03833

Title: CIRCUIT BOARD, ROMEO ZERO, GEN2 BOARD
Size: A
Number: 7404337
Revision: 00
Date: 3/30/23
Sheet 1 of 1
File:
Drawn By: MM



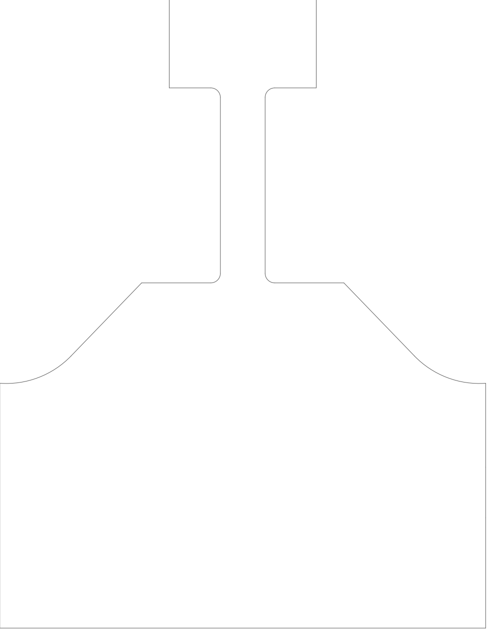
TopPaste

Board Outline

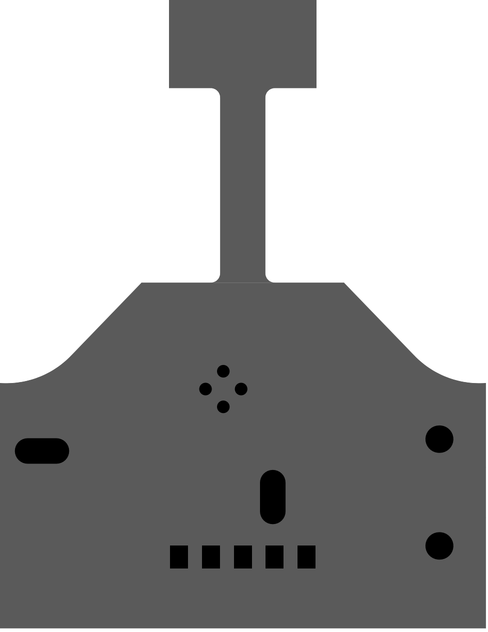


Top Coverlay

Board Outline

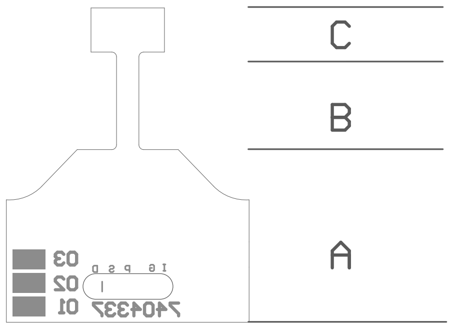


Board Outline



Bottom Coverlay

Board Outline



PCB Fab Notes (dimensions in mm)---

1. Refer to 7404337 drawing pdf for additional requirements.
2. For PCB stackup ('A', 'B', 'C'), refer to stackup file in Project Outputs > FAB folder.
3. Finish: Exposed conductive pads and traces plated with ENIG per IPC-4552.
4. Soldermask: CM is allowed to alter soldermask expansion as required.
5. Layer-to-layer registration <0.152.
6. PCB to be lead free and RoHS compliant, and compatible with RoHS assembly methods.
7. Inner layer copper pullback from board edge allowed.
8. Silkscreen: white, permanent, non-conductive ink. Keep clear of solder pads.
9. No controlled impedance requirements.
10. Hole tolerance: +/-.076 (drill position); diameter +/-.076 (PTH).
11. Coverlay may be added over black in the C section of stackup to create smaller solder dams to prevent solder bridges.
12. There are two additional files for top paste and solder for the layer 3 top.
13. Stiffener on the bottom side of section A needs a mechanical cutout for 5-pin, see drawing.
14. Mounting slots for J2 show plating through the stiffener that shoudln't be there the plating should not extend to stiffener.
15. Bottom Coverlay Print should be printed on the bottom of the stiffener, not the bottom of the flex circuit.

Bottom Overlay

PCA Assembly Notes--

1. Assemble per IPC-A-610, Class 2. Double sided assembly.
2. Lead free, No Wash, RoHS compliant assembly.

4. ESD sensitive assembly. Package and handle in accordance with ESD procedures.
5. Optical components at D1. Keep D1 lens clear of debris and contaminants.
6. No component at J3, programming pads. Keep pads clear of contaminants.
7. Refer to 7404337 dwg pdf for additional requirements.
8. The 7404337 board will be used for three different BOMS

Fab Notes
Assembly Notes
Cutout in Stiffener

Board Outline

SIG SAUER
18 Industrial Drive Exeter, NH 03833

Title CIRCUIT BOARD, ROMEO ZERO, GEN2 BOARD		
Size A	Number 7404337	Revision 00
Date: 3/30/23		Sheet 1 of 1
File:		Drawn By: MM